

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

JPW

Applicant: Brian Taggart et al.

Title: USE OF DIRECT GOLD SURFACE FINISH ON A COPPER WIRE-BOND SUBSTRATE,  
METHODS OF MAKING SAME, AND METHODS OF TESTING SAME (As Amended)

Docket No.: 884.887US1

Filed: June 27, 2003

Examiner: Cathy Lam



Serial No.: 10/608,059

Due Date: October 21, 2004

Group Art Unit: 1775

**Mail Stop Amendment**

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

We are transmitting herewith the following attached items (as indicated with an "X"):

☒ A return postcard.

☒ An Amendment and Response Under 37 C.F.R. 1.111 (10 Pages).

If not provided for in a separate paper filed herewith, Please consider this a PETITION FOR EXTENSION OF TIME for sufficient number of months to enter these papers and please charge any additional fees or credit overpayment to Deposit Account No. 19-0743.

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.

Customer Number 21186

By: Ann M. McCrackin  
Atty: Ann M. McCrackin  
Reg. No. 42,858

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Mail Stop Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this 21 day of September 2004.

Chris Hammond

Name

Chris Hammond  
Signature

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.

(GENERAL)



S/N 10/608,059

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	Brian Taggart et al.	Examiner:	Cathy Lam
Serial No.:	10/608,059	Group Art Unit:	1775
Filed:	June 27, 2003	Docket No.:	884.887US1
Title:	USE OF DIRECT GOLD SURFACE FINISH ON A COPPER WIRE-BOND SUBSTRATE, METHODS OF MAKING SAME, AND METHODS OF TESTING SAME (As Amended)		
Assignee:	Intel Corporation	Customer No:	21186

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AMENDMENT AND RESPONSE UNDER 37 CFR § 1.111

MS Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

This responds to the Office Action mailed on July 21, 2004. Please amend the above-identified patent application as follows.

**AMENDMENT AND RESPONSE UNDER 37 CFR § 1.111**

Serial Number: 10/608,059

Filing Date: June 27, 2003

Title: USE OF DIRECT GOLD SURFACE FINISH ON A COPPER WIRE-BOND SUBSTRATE, METHODS OF MAKING SAME, AND METHODS OF TESTING SAME (As Amended)

Assignee: Intel Corporation

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Dkt: 884.887US1 (INTEL)

**IN THE TITLE**

Please amend the title of the application as follows:

USE OF DIRECT GOLD SURFACE FINISH ON A COPPER WIRE-BOND  
SUBSTRATE, METHODS OF MAKING SAME, AND METHODS OF TESTING SAME